Datasheet

AEC-Q101 Qualified

ROHM

Nch 30V 4.5A Power MOSFET

V_{DSS}	30V
R _{DS(on)} (Max.)	38 m Ω
I _D	4.5A
P_{D}	1.25W

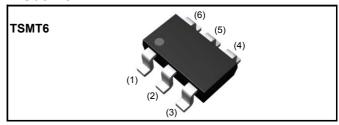
Features

- 1) Low on resistance.
- 2) Built-in G-S Protection Diode.
- 3) Small Surface Mount Package (TSMT6).
- 4) Pb-free lead plating; RoHS compliant

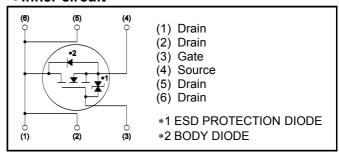
Application

DC/DC converters

Outline



•Inner circuit



Packaging specifications

	Packaging	Taping
	Reel size (mm)	180
Typo	Tape width (mm)	8
Туре	Basic ordering unit (pcs)	3,000
	Taping code	TR
	Marking	QL

●Absolute maximum ratings(T_a = 25°C)

Parameter	Symbol	Value	Unit
Drain - Source voltage	$V_{ m DSS}$	30	V
Continuous drain current	I _D *1	±4.5	Α
Pulsed drain current	I _{D,pulse} *2	±18	Α
Gate - Source voltage	V_{GSS}	±20	V
Power dissipation	P _D *3	1.25	W
rowei dissipation	P _D *4	0.6	W
Junction temperature	T _j	150	°C
Range of storage temperature	T _{stg}	-55 to +150	°C

●Thermal resistance

Parameter	Symbol	Values			Unit
- Farametei	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - ambient	R _{thJA} *3	-	-	100	°C/W
Thermal resistance, junction - ambient	R _{thJA} *4	-	-	208	°C/W

$\bullet Electrical\ characteristics (T_a$ = $25^{\circ}C)$,unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit	
r ai ai nietei	Symbol	TIDOI CONDITIONS		Тур.	Max.	OTIIL	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$, $I_D = 1mA$	30	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I _D =1mA referenced to 25°C	1	26	-	mV/°C	
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 30V, V_{GS} = 0V$	-	-	1	μΑ	
Gate - Source leakage current	I_{GSS}	$V_{GS} = 20V, V_{DS} = 0V$	ı	ı	10	μΑ	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = 10V$, $I_D = 1mA$	1.0	ı	2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{(GS)th}}{\Delta T_{j}}$	I _D =1mA referenced to 25°C	-	-2.8	-	mV/°C	
		V _{GS} =10V, I _D =4.5A	-	27	38		
Static drain - source	D *5	V _{GS} =4.5V, I _D =4.5A	-	36	51	m()	
on - state resistance	$R_{DS(on)}$	V _{GS} =4.0V, I _D =4.5A	1	40	56	mΩ	
		V _{GS} =10V, I _D =4.5A, T _j =125°C	ı	50	70		
Gate input resistannce	R_{G}	f = 1MHz, open drain	-	6	-	Ω	
Transconductance	9 _{fs} *5	V _{DS} =10V, I _D =4.5A	3.5	7.0	-	S	

^{*1} Limited only by maximum temperature allowed.

^{*2} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*3} Mounted on a ceramic board (30×30×0.8mm)

^{*4} Mounted on a FR4 (15×20×0.8mm)

^{*5} Pulsed

•Electrical characteristics($T_a = 25$ °C)

Parameter	Symbol	Conditions	Values			Unit
r ai ai ii etei	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C _{iss}	V _{GS} = 0V	-	520	-	
Output capacitance	C_{oss}	V _{DS} = 10V	-	150	-	pF
Reverse transfer capacitance	C_{rss}	f = 1MHz	-	95	-	
Turn - on delay time	$t_{d(on)}^{*5}$	V _{DD} ≃ 15V, V _{GS} = 10V	-	12	-	
Rise time	t _r *5	I _D = 2.25A	-	19	-	no
Turn - off delay time	${\rm t_{d(off)}}^{*5}$	$R_L = 6.67\Omega$	-	41	-	ns
Fall time	t_f^{*5}	$R_G = 10\Omega$	-	14	-	

•Gate Charge characteristics($T_a = 25$ °C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	${\sf Q_g}^{*5}$	$V_{DD} \simeq 15V$, $I_D=4.5A$ $V_{GS} = 5V$	-	6.8	9.5	
Total gate charge	$V_{DD} \simeq 15V$, $I_D=4.5A$ $V_{GS} = 10V$	-	13	-	nC	
Gate - Source charge	Q _{gs} *5	$V_{DD} \simeq 15V$, $I_D=4.5A$ $V_{GS} = 5V$	1	1.6	_	
Gate - Drain charge	Q _{gd} *5	$V_{GS} = 5V$	-	2.3	-	

●Body diode electrical characteristics (Source-Drain)(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
r ai ai ii etei	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Inverse diode continuous, forward current	l _S *1	T _a = 25°C	-	-	1	А
Forward voltage	V _{SD} *5	$V_{GS} = 0V, I_s = 1.0A$	-	ı	1.2	V

Fig.1 Power Dissipation Derating Curve

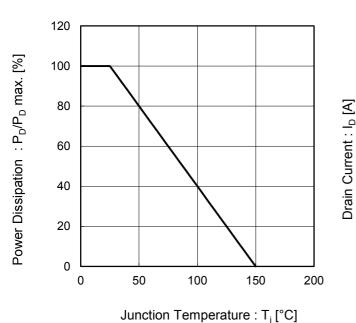
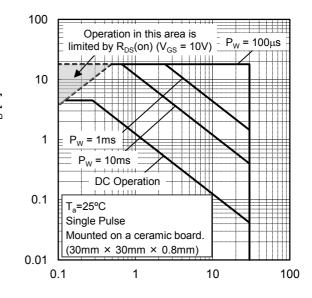
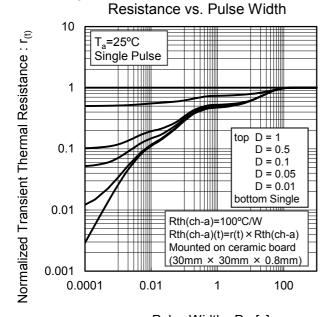


Fig.2 Maximum Safe Operating Area



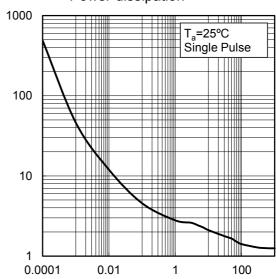
Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal



Pulse Width : P_W [s]

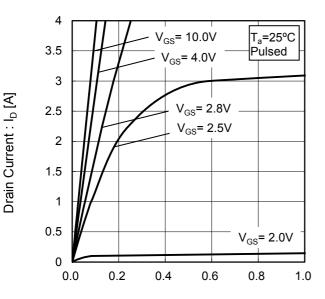
Fig.4 Single Pulse Maximum Power dissipation



Pulse Width: P_W [s]

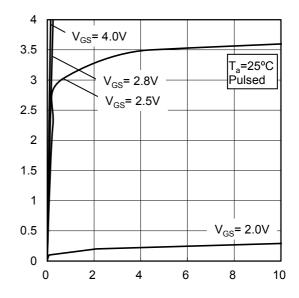
Peak Transient Power: P(W)

Fig.5 Typical Output Characteristics(I)



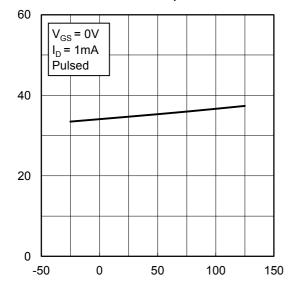
Drain - Source Voltage : V_{DS} [V]

Fig.6 Typical Output Characteristics(II)



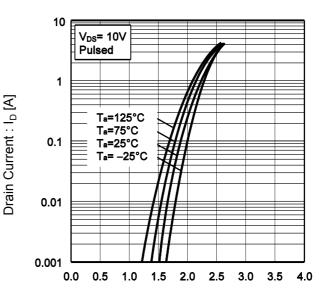
Drain - Source Voltage : V_{DS} [V]

Fig.7 Breakdown Voltage vs. Junction Temperature



Junction Temperature : T_j [°C]

Fig.8 Typical Transfer Characteristics



Gate - Source Voltage : V_{GS} [V]

Drain - Source Breakdown Voltage: V_{(BR)DSS} [V]

Drain Current : I_D [A]

Gate Threshold Voltage: V_{GS(th)} [V]

•Electrical characteristic curves

Fig.9 Gate Threshold Voltage

vs. Junction Temperature

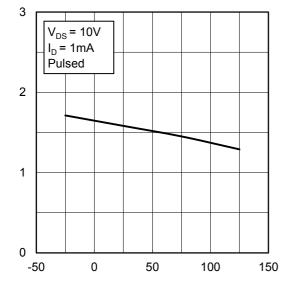
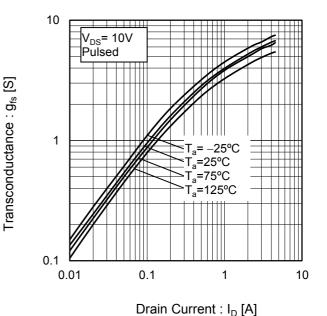
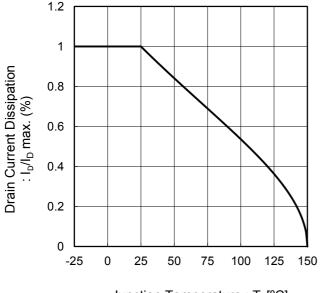


Fig.10 Transconductance vs. Drain Current



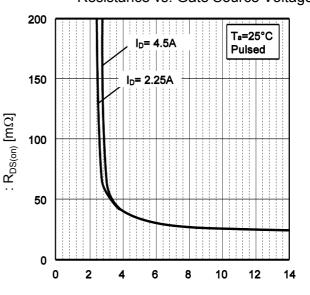
Junction Temperature : T_i [°C]

Fig.11 Drain CurrentDerating Curve



Junction Temperature : T_i [°C]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



Gate - Source Voltage : V_{GS} [V]

Static Drain - Source On-State Resistance

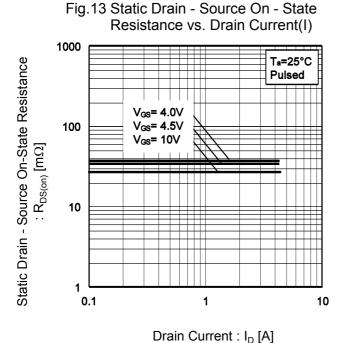


Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature 60 Static Drain - Source On-State Resistance 50 40 $:R_{\text{DS(on)}}\left[\text{m}\Omega\right]$ 30 20 $V_{GS} = 10V$ $I_D = 4.5A$ Pulsed 10 0 -50 -25 0 25 50 75 100 125 150

Junction Temperature : T_i [°C]

Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II) 1000 V_{GS}= 10V Static Drain - Source On-State Resistance Pulsed Ta=125°C Ta=75°C Ta=25°C 100 Ta= -25°C $:R_{DS(on)}\left[m\Omega \right]$ 10 0.1 1 10 Drain Current : I_D [A]

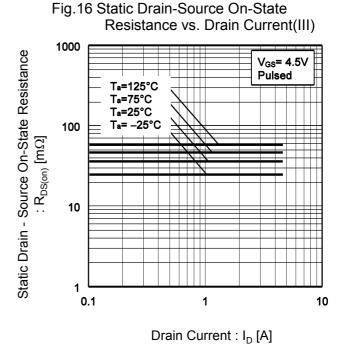




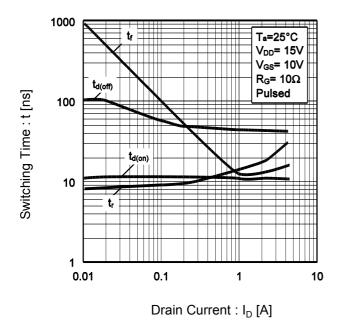
Fig.17 Static Drain - Source On - State Resistance vs. Drain Current(IV) 1000 Static Drain - Source On-State Resistance V_{GS}= 4.0V Pulsed Ta=125°C Ta=75°C Ta=25°C Ta= -25°C 100 $:R_{\mathsf{DS}(\mathsf{on})}\left[\mathsf{m}\Omega \right]$ 10 0.1 1 10

Fig.18 Typical Capacitance vs. Drain - Source Voltage 10000 Ta=25°C f=1MHz V_{GS}= 0V 1000 Capacitance: C [pF] Coss 100 10 0.01 0.1 10 100

Drain - Source Voltage : V_{DS} [V]

Fig.19 Switching Characteristics

Drain Current : I_D [A]



10 Ta=25°C 9 V_{DD}= 15V $I_D = 7.5A$ $R_G = 10\Omega$ Pulsed 7

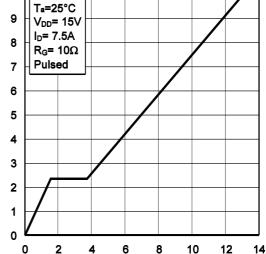
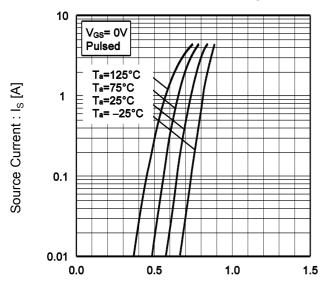


Fig.20 Dynamic Input Characteristics

Total Gate Charge : Qq [nC]

Gate - Source Voltage : V_{GS} [V]

Fig.21 Source Current vs. Source Drain Voltage



Source-Drain Voltage : V_{SD} [V]

● Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

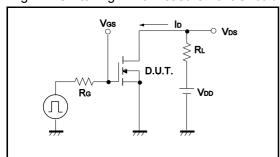


Fig.2-1 Gate Charge Measurement Circuit

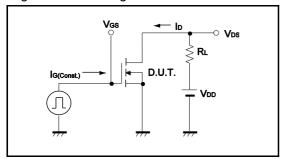


Fig.1-2 Switching Waveforms

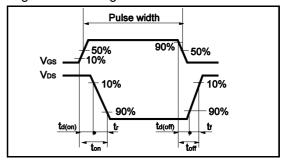
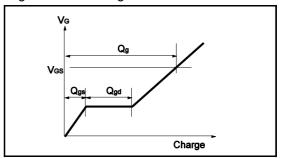
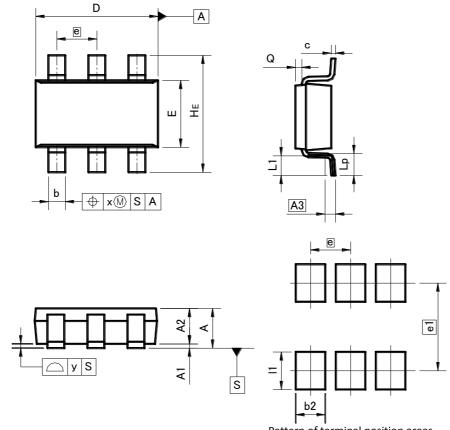


Fig.2-2 Gate Charge Waveform



●Dimensions (Unit: mm)





Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	_	1.00	_	0.039
A1	0.00	0.10	0.000	0.004
A2	0.75	0.95	0.030	0.037
A3	0.3	25	0.0	10
b	0.35	0.50	0.014	0.020
С	0.10	0.26	0.004	0.010
D	2.80	3.00	0.110	0.118
Е	1.50	1.80	0.059	0.071
е	0.9	95	0.0	37
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.05	0.25	0.002	0.010
х	_	0.20	_	0.008
У	_	0.10	_	0.004

DIM	MILIMETERS		INC	HES
DIIVI	MIN	MAX	MIN	MAX
b2		0.70	_	0.028
e1	2.10		0.0	83
l1	_	0.90	_	0.035

Dimension in mm / inches

Notice

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(Note1) Medical Equipment Classification of the Specific Applications

Ì	JÁPAN	USA	EU	CHINA
Γ	CLASSⅢ	CL ACCTI	CLASS II b	CI VCCIII
Γ	CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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RSQ045N03FRA - Web Page

Distribution Inventory

Part Number	RSQ045N03FRA
Package	TSMT6
Unit Quantity	3000
Minimum Package Quantity	3000
Packing Type	Taping
Constitution Materials List	inquiry
RoHS	Yes